



100% Material Declaration Data Sheet for SFVA784

PK808 (v1.0) June 16, 2016

Average Weight : **6.1500 g**

Component	Substance Description	CAS # or Description	% of component	Use in product	Component weight / substance weight (in grams)	Component % of total
Silicon die	Si	7440-21-3	100.00	basis	0.328554	5.342%
					0.013405	
Bump	Sn	7440-31-5	98.20	basis	0.013164	0.218%
	Ag	7440-22-4	1.80	basis	0.000241	
					0.048800	
Underfill	Bisphenol F type liquid epoxy	9003-36-5	15.00	basis	0.007320	0.793%
	1,6-Bis(2,3-epoxypropoxy)naphthalene	27610-48-6	10.00	basis	0.004880	
	Bisphenol A type liquid epoxy resin	25068-38-6	5.00	basis	0.002440	
	Amine type hardener	trade secret	10.00	basis	0.004880	
	Silicon dioxide	60676-86-0	58.00	filler	0.028304	
	Carbon black	1333-86-4	1.00	color agent	0.000488	
	Additives	trade secret	1.00	additives	0.000488	
				0.007168		
Solder paste	Sn	7440-31-5	96.50	metal	0.006917	0.117%
	Ag	7440-22-4	3.00	metal	0.000215	
	Cu	7440-50-8	0.50	metal	0.000036	
				3.360000		
Lid	Cu	7440-50-8	99.64	Main material	3.304560	54.634%
	Ni	7440-02-0	0.36	Main material	0.055440	
				0.920000		
Lid Adhesive	Aluminium Oxide Al2O3	trade secret	80.00	Main material	0.736000	14.959%
	Dimethyl siloxane, dimethylvinyl-terminated	68083-19-2	20.00	Main material	0.184000	
				0.379008		
Solder ball	Sn	7440-31-5	96.50	Main material	0.365743	6.163%
	Ag	7440-22-4	3.00	Main material	0.011370	
	Cu	7440-50-8	0.50	Main material	0.001895	
				0.001200		
Capacitor 1	BaTiO3 type	1304-28-5	30.22	Ceramic	0.000363	0.020%
	Titanium dioxide	13463-67-7	15.11		0.000181	
	Misc	-	5.04		0.000060	
	Ni	7440-02-0	33.44	Inner electrode	0.000401	
	Cu	7440-50-8	11.87	Out electrode	0.000142	
	Silicon dioxide	7631-86-9	1.06		0.000013	
	diboron trioxide; boric oxide	1303-86-2	0.26		0.000003	
	Ni	7440-02-0	0.81	Plating1	0.000010	
	Sn	7440-31-5	2.19	Plating2	0.000026	
					0.000920	
Capacitor2	BaTiO3 type	1304-28-5	31.67	Ceramic	0.000291	0.015%
	Titanium dioxide	13463-67-7	15.83		0.000146	
	Misc	trade secret	5.28		0.000049	
	Ni	7440-02-0	26.67	Inner Electrode	0.000245	
	Cu	7440-50-8	15.10	Outer Electrode	0.000139	
	Silicon dioxide	7631-86-9	1.34		0.000012	
	diboron trioxide; boric oxide	1303-86-2	0.33		0.000003	
	Ni	7440-02-0	1.00	Plating1	0.000009	
	Sn	7440-31-5	2.78	Plating2	0.000026	
					1.090945	
Substrate	Copper	7440-50-8	31.29		0.341357	17.739%
	Tin	7440-31-5	0.85		0.009273	
	Silver	7440-22-4	0.03		0.000327	
	Core	N/A	49.97		0.545145	
	ABF	N/A	15.72		0.171497	
	Solder Mask	N/A	2.14		0.023346	

Revision History

Date	Version	Description of Revisions
6/16/2016	1.0	Initial Xilinx release.

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